

SEMICONDUCTOR PACKAGE STRUCTURE AND MANUFACTURING METHOD

ABSTRACT

The embodiments of the present application disclose a semiconductor package structure and a manufacturing method. The semiconductor package structure includes: a first package structure, including an intermediary layer and a molding compound, where a plurality of first connection pads are disposed on the intermediary layer, and the molding compound wraps the intermediary layer and is coplanar to the plurality of first connection pads; and a second package structure, disposed on the intermediary layer and electrically connected to the plurality of first connection pads. A gap is formed between the first package structure and the second package structure.

[Fig. 1]